

PRODUCT SPECIFICATION

MONO LCD MODULE MODEL: ELC1602Q8FSW1B-A4 Ver:1.0

< >> Preliminary Specification

< ◆> Finally Specification

CUSTOMER'S APPROVAL										
CUSTOMER:										
SIGNATURE: DATE:										

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	Ву

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1. Features

The features of LCD are as follows

* Display mode : Form:

ST7066U-0A : FSTN / Transflective / positive

* Display format : 16X2 Characters

* Interface Input Data : 8 Bit 6800

* Driving Method : 1/16Duty, 1/4Bias

* Viewing Direction : 6 O'clock * Backlight : LED /White

* Sample NO. : C1602Q8FSW1B-C0 _01/20130927

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	122.0(W) x44.0(H) x13.3Max(T)	mm
Viewing Area	99.0(W) x 25(H)	mm
Activity Area	94.84(W)x20(H)	mm
Character Font	5x7 Dots +Cursor	-
Character Size	4.84(W)x9.66(H)	mm
Character Pitch	6(W)x10.34(H)	mm
Dot Size	0.92(W)x1.1(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V _{DD} – Vss	-0.3	ı	7	V
Supply Voltage For LCD Drive	V _{OP} = V _{DD} -V ₀	Vcc -10.0	-	Vcc +0.3	V
Input Voltage	Vin	-0.3	-	Vcc+0.3	V
Operating Temp.	Тор	0	-	+50	°C
Storage Temp.	Tst	-10	-	+60	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

3-2 ELECTICAL CHARACTERISTICS

3-2-1.DC CHARACTERISTICS (VDD=4.5V~5.5V,Ta=25°C)

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	V _{DD} – V _{ss}	Ta = 25 °C	3.0	3.3	3.6	\
LCD Dri	ive	V _{OP} =V _{DD} -V ₀		2.9	3.2	3.3	V
Input Voltage	"H" Level	V _{IH}		0.7Vcc	1	Vcc	V
	"L" Level	V _{IL}		0.3	-	0.6	V
Frame Frequency		f _{FLM}	$V_{DD} = 3.3V \pm 5\%$	-	-	75	Hz
Current Cons	umption	I _{DD}		-	1.85	-	mA

3-3. BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF	Ta = 25 °C	-	30	50	mA
Power Dissipation	PD	1a - 25 C	-	-	150	mW
Reverse Current	IR	VR=5V	-	-	2*10	uA

3-3-2. Electrical-optical Characteristics

Item	Symbol	Condition	min		Тур		Max		Unit
Forward Voltage	Forward Voltage IF -		30		36		mA		
Average Luminous Intensity	lv		100		250		-		cd/m ²
Colour coordinate		Ta = 25 °C	Х	Υ	Х	Υ	X	Υ	
Colour Coolullate		Vf=3.0V	0.25	0.25	0.28	0.28	0.31	0.31	_
Module luminance			25		37		-		cd/m ²
Uniformity			75	5%		-	•	-	

The backlight brightness is measured without LCD panel

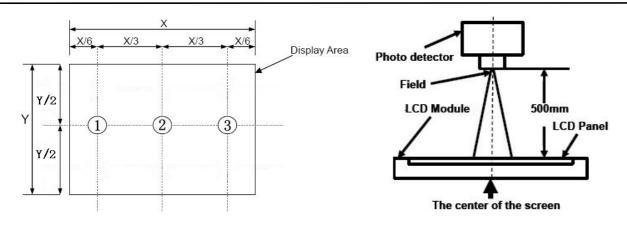
For operation above 25°C, The Ifm Ifp &Pd must be derated,the current derating is -0.36mA/°C for DC drive and -0.86 mA/°C for Pulse drive, the Power dissipation is -0.75mW/°C. The produt working current must not more than the $60\,\%$ of the Ifm or Ifp according to the working temperature.

The module brightness is measured with LCD showing nothing

3-3-3. Luminance Measuring

Surface Luminance: L_V = average (L_{P1} : L_{P3})

Uniformity = Minimal $(L_{P1}:L_{P3})$ / Maximal $(L_{P1}:L_{P3})$ * 100%

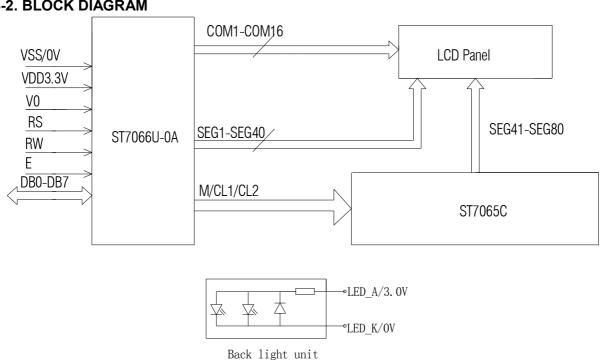


4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1. INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	LED_K	Backlight (-) /0V
2	LED_A	Backlight (+)/3.0V
3	VSS	Ground
4	VDD	Supply voltage for logical circuit/3.3V
5	V0	Supply voltage for LCD driving
		A signal for selecting registers:
6	RS	1: Data Register (for read and write)
		0: Instruction Register (for write)
7	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
8	E	Enable signal for reading or writing data.
9-16	DB0-DB7	8 Bit Data Bus

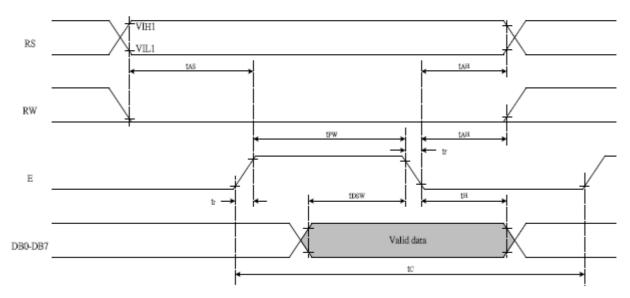
4-2. BLOCK DIAGRAM



5. TIMING CHARACTERISTICS

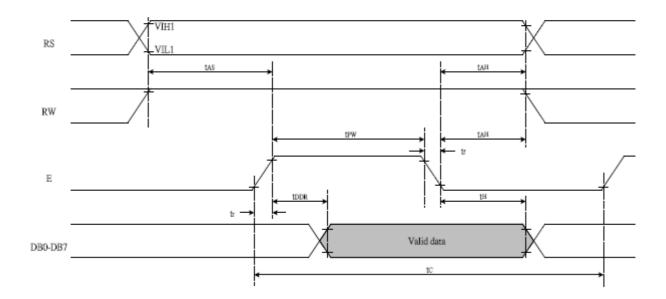
5-1. Write mode

Writing data from MPU to \$T7066U

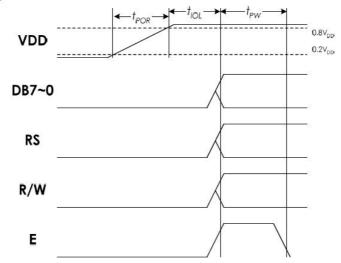


5-2. Read mode

Reading data from \$T7066U to MPU



5-3 Power Supply Conditions



Symbol	Characteristics	Description	Min.	Тур.	Max.	Unit			
tPOR	Power rise time	Power rise time that will trigger internal power on reset circuit	0.1		100	ms			
tIOL	I/O Low time	The period that I/O is kept low.	40			ms			
tPW	Enable pulse width	Please refer to the following tables.							

- During tPOR, VDD noise should be reduced (especially close to 2.0V). Otherwise the Power-ON-Reset function might be triggered several times and maybe cause unexpected result.
- 2. During tIOL, the I/O ports of the interface (control and data signals) should be kept at "Low".

Issued Date:2013-9-27 Doc. No.: 5-4 8-bit Interface (fosc=270KHz) POWER ON Wait time >40mS After Vcc >4.5V **Function set** BF cannot be RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 checked before this instruction. F X 0 0 1 1 N X Wait time >37uS **Function set** BF cannot be RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 checked before this instruction. 0 0 0 1 F X 0 1 X Wait time >37uS **Display ON/OFF control** RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 0 0 1 D C В Wait time >37uS Display clear RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 0 0 1 Wait time >1.52mS **Entry mode set** RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 0 0 0 1 I/D S Initialization end

Issued Date:2013-9-27 Doc. No.: 5-5 4 bit Interface (fosc=270KHz) POWER ON Wait time >40mS After Vcc >4.5V **Function set** BF cannot be RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 checked before this instruction. 1 1 X Wait time >37uS **Function set** BF cannot be RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 | checked before 0 1 0 X X X X this instruction. 0 0 N X X X X X Wait time >37uS **Function set** BF cannot be RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 checked before 0 0 1 X X X this instruction. 0 X 0 N X X X Wait time >37uS Display ON/OFF control RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 X X 0 0 X X C 0 0 1 D В X X X Wait time >37uS Display clear RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 X X X 0 1 0 X Wait time >1.52mS Entry mode set RS | R/W | DB7 | DB6 | DB5 | DB4 | DB3 | DB2 | DB1 | DB0 0 0 0 0 0 X X X X I/D X 0 0 S X X

Initialization end

6. COMMAND LIST

Instruction Table:

Instruction Tab				Inst	ructi	on (Code	,				Description
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Time (270KHz)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.52 ms
Return Home	0	0	0	0	0	0	0	0	1	х	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.52 ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	s	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 us
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1:entire display on C=1:cursor on B=1:cursor position on	37 us
Cursor or Display Shift	0	0	0	0	0	1	s/c	R/L	х	х	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	37 us
Function Set	0	0	0	0	1	DL	N	F	x	х	DL:interface data is 8/4 bits N:number of line is 2/1 F:font size is 5x11/5x8	37 us
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	37 us
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	37 us
Read Busy flag and address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 us
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM)	37 us
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM)	37 us

Note:

Be sure the ST7066U is not in the busy state (BF = 0) before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Instruction Table for the list of each instruction execution time.

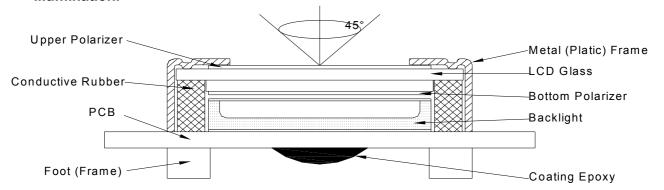
7. CHARACTER GENERATOR ROM

NO.7066-0A

	<u> -מטט</u>	ᄱ														
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	(7)		8													
0111	(8)							W					×			
1000	(1)							**								×
1001	(2)															
1010	(3)							×								
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

8. QUALITY SPECIFICATIONS

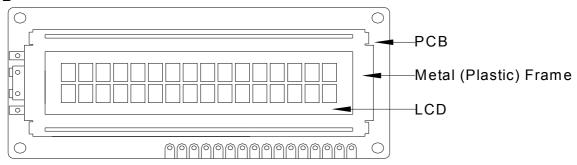
- 8 1. LCM Appearance and Electric inspection Condition
 - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



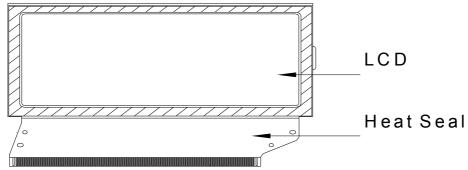
2. View Angle: with in 45° around perpendicular line.

8-2. Definition

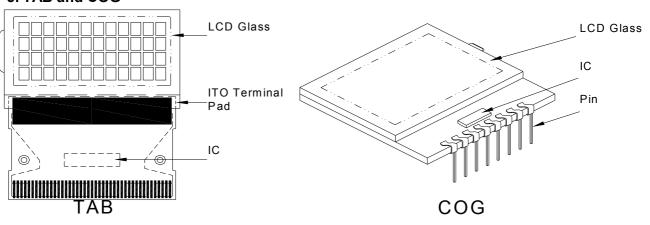
1. COB



2. Heat Seal



3. TAB and COG



8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65% Minor defect: AQL = 1.5%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards				
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject			
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject			
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject			
Major	PCB cutting defect	Exceed the dimension of drawing	Reject			

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD	<i>θ</i> ≤ 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards				
Major	Crack / breakage	Any	Reject			
		W	L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1		
		w <u>></u> 0.3mm	Any	0		
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.				
				Acceptable of Dents / Pricks		
		Φ<	2			
	Frame Dent , Prick	1.0<	1			
Minor	$\Phi = \frac{L + W}{2}$	1.5	0			
	2	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing				
Minor	Metal Frame Oxidation		Any rust			

4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standards			
Minor	Tilte	Tilted soldering Within the angle +5°		Acceptable		
Minor	Uneven s	older joint /bump		Reject		
			Expose the conductive line	Reject		
Minor	Hole	$\Phi = \frac{L + W}{2}$	Ф > 1.0mm	Reject		
Minor	Position shift		Y > 1/3D	Reject		
MITIO	-\hat{X}	X > 1/2Z		Reject		

5. Screw

Defect Inspection Item		Inspection Standards			
Major	Screw missing/loosen		Reject		
Minor	Screw oxidation	Any rust	Reject		
Minor	Screw deformation	Difficult to accept screw driver	Reject		

6. Heat-seal \ TCP \ FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIII IOI	X	X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		Ф <u><</u> 0.10mm	Ignore				
		0.10<⊕ <u><</u> 0.15mm					
Minor	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1				
		Ф>0.2mm	0				
		The distance between any two spots should be Any spot/dot/void outside of viewing area is acce					
Minor	Protective film tilt	Not fully cover LCD					
Major	COG coating	Not fully cover ITO circuit					

8. Electric Inspection

Defect Inspection Item		Inspection Standards				
Major	Short		Reject			
Major	Open		Reject			

9. Inspection Specification of LCD

Defect	Inspect Item			Inspection Standards					
			W		/<0.03		03 <w<0.0< td=""><td></td><td>V>0.05</td></w<0.0<>		V>0.05
Minor		* Glass Scratch	L	*	L<5		L<3	<u> </u>	Any
	Linear Defect	* Fiber and Linear	Polarizer Scratch ACC					Reject	
		material	Note	L is the I	ength and \	V is th	e width of	the de	efect
		* Foreign material	Φ	Φ <u><</u> 0.1		0.15	0.15<⊕ <u><</u> 0	.2	⊕>0.2
	Black Spot and			3EA / 100mm	2 2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.					
		* Unobvious		Φ	<u><</u> 0.3	0.3	<⊕ <u><</u> 0.5	0.	5<⊕
	White Spot	transparant foreign material between	ACC. NO.	3EA /	100mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.					
			Φ	Ф <u><</u> 0.10	_	<u><</u> 0.20	0.20<⊕ <u><</u> 0.25		Ф>0.25
		w w	ACC. NO.	3EA / 100mm	2 2		1		0
Minor	Segment Defect			W is more than 1/2 segment width Reje				Reject	
			Note	Φ= L Distance	+ W 2 between to	vo def	ect is 10m	m	
			Φ	Φ <u><</u> 0.10	0.10<Φ:	<u><</u> 0.20	0.20<⊕≤	<u><</u> 0.25	Φ>0.25
N diam a sa	Protuberant	w	W		W <u><</u> 1/2 W <u><</u> 0		W <u><</u> 1/2 W <u><</u> 0.		Ignore
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm	2 2		1		0
			1. Seg	yment					
			В		3 <u><</u> 0.4mm		3 <u><</u> 1.0mm		1.0mm
Minor	Assembly		B-		B-A<1/2B		A<0.2		<0.25
IVIII IOI	Mis-alignment	H _B -1 -1 -A	Judge Acceptable Acceptable Acceptable						eptable
			2. Dot Matrix Deformation>2°						Reject
Minor	Stain on LCD Panel Surface	man had been been been been been been been bee	Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"						

9. RELIABILITY

NO.	ltem	Condition	Criterion
1	High Temperature Operating	50℃, 96Hrs	
2	Low Temperature Operating	0°C, 96Hrs	
3	High Humidity	40℃, 90%RH, 96Hrs	
4	High Temperature Storage	60°C, 96Hrs	
5	Low Temperature Storage	-10°C, 96Hrs	No defect in cosmetic and opera tional function allowable.
		Random wave	Total
6	Vibration	10 ~ 100Hz	current Consumption should be below double of initial value.
	Vibration	Acceleration: 2g	
		2 Hrs per direction(X,Y,Z)	
		0°C to 25°C to 50°C	
7	Thermal Shock	(60Min) (5Min) (60Min)	
_		16Cycles	
		Contract Discharge Voltage: +1 ~ 4kV and –1 ~ –4kV	There will be discharged ten times at every discharging
8	ESD Testing	Air Discharge Voltage: +1 ~ 6kV and –1 ~ -6kV	voltage cycle. The voltage gap is 1kV.

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.3) Thereliability test quantity no less than 8 pcs

Issued Date:2013-9-27 Doc. No.:

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is reequired.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

- When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

